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Oggetto : SECO strengthens collaboration with

Qualcomm at Embedded World 2025 to deliver

cutting-edge industrial solutions

Testo del comunicato

Vedi allegato





PRESS RELEASE

SECO strengthens collaboration with Qualcomm at Embedded World 2025 to deliver cutting-edge industrial solutions

Arezzo, Italy, March 6, 2025 – SECO, a leading global provider of end-to-end solutions for embedded computing, announced the expansion of its technology collaboration with Qualcomm Technologies, Inc. This collaboration further strengthens SECO's commitment to developing and delivering innovative industrial solutions utilizing advanced Qualcomm Dragonwing™ products and Snapdragon® X Series platforms. The fruits of this collaboration will be showcased at embedded world 2025, held from March 11 to 13 in Nuremberg, Germany, where attendees can discover firsthand the latest advancements from this collaboration.

SECO is broadening its product portfolio based on Dragonwing processors, offering a range of high-performance, energy-efficient embedded solutions tailored for industrial applications.

In the SMARC form factor, SECO offers **SMARC System-on-Modules (SoMs)** featuring the Dragonwing **QCS5430** and Dragonwing **QCS6490** processors: the <u>SOM-SMARC-QCS6490</u> and the <u>SOM-SMARC-QCS6490</u> and

For **Single Board Computers (SBCs) & Custom Applications**, SECO is actively developing SBCs based on the Dragonwing **IQ-615 processor**, enabling powerful and flexible embedded solutions for industrial HMIs, robotic controllers, smart vision, and intelligent edge applications. A SoM variant based on the Dragonwing **IQ-615** is also being evaluated to meet the evolving needs of industrial customers.

In the field of COM Express solutions, SECO is developing a **COM Express Computer-On-Module (COM) with Snapdragon X Series Platforms**, offering top-tier computing power, Al acceleration, and high-efficiency processing with Windows support. The solution will be available across all **Snapdragon X Elite**, **Snapdragon X Plus**, and **Snapdragon X Platforms**, providing flexibility for a wide range of performance requirements.

Finally, for **Next-Generation AI Solutions**, SECO is evaluating **AI-optimized platforms** utilizing Dragonwing **IQ8 and IQ9** Series processors for AI Clea applications. These platforms will power advanced **AI SBCs and AI Box solutions**, enabling industrial customers to integrate **real-time intelligence**, **edge computing**, **and machine learning capabilities** into their operations.

"SECO is committed to providing state-of-the-art industrial solutions, and our collaboration with Qualcomm Technologies enables us to bring high-performance, Al-driven computing to the edge," said **Davide Catani, Chief Technology Officer at SECO**. "With our expanding portfolio of solutions based on Qualcomm and Snapdragon platforms, we empower industrial customers to harness the full potential of Al, IoT, and edge computing."

"Advancements in AI are increasing the demand for more efficient and powerful edge solutions. We are pleased to expand our technology collaboration with SECO as they develop new embedded products that unlock the advanced computing and AI capabilities of our Dragonwing and Snapdragon processors to accelerate innovation in the industrial markets," said Enrico Salvatori, SVP and President at Qualcomm Europe, Inc.





PRESS RELEASE

SECO's solutions will be showcased at **embedded world 2025**, both at SECO's and Qualcomm Technologies' booths, where visitors will have the opportunity to learn more about the latest innovations in industrial edge computing and experience live demonstrations of a **Voice Command and LLM Technical Assistant**. The system answers technical questions based on documentation of various electronic boards. It uses a Retrieval-Augmented Generation (RAG) system that combines an LLM with a semantic search in an optimized, custom-built vector database derived from SECO documentation. Users can interact via voice commands or by typing with a keyboard. Responses will be provided both on-screen and via SECO's Text-to-Speech model, allowing users to read and listen to the answers.

For more information, visit <u>SECO's website</u> or meet SECO at **embedded world 2025**, Hall 1, Booth 320.





PRESS RELEASE

SECO

SECO (IOT.MI) is a high-tech company that develops and manufactures cutting-edge solutions for the digitalization of industrial products and processes. SECO's hardware and software offerings enable B2B companies to easily introduce edge computing, Internet of Things, data analytics, and artificial intelligence to their businesses. SECO's technology spans across multiple fields of application, serving more than 450 customers across sectors such as medical, industrial automation, fitness, vending, transportation, and many others. Through live monitoring and smart control of in-the-field devices, SECO solutions contribute to low environmental impact business operations via a more efficient use of resources.

For more information: http://www.seco.com/

Contacts

SECO S.p.A.
Clarence Nahan
Head of Corporate Development & Investor Relations
Tel. +39 0575 26979
investor.relations@seco.com

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